LBI-30032M

MAINTENANCE MANUAL 406-512 MHz RF ASSEMBLIES 19D417075G9-G38, 19B233690G1-G20 AND IF FILTER BOARDS 19C320523G2-G3, 19C331148G1-G2

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DESCRIPTION

The RF Assembly uses five tuned helical resonators to provide front end RF selectivity with no gain. A UHS preamplifier assembly is available that can be used with the receiver to improve sensitivity.

Mixer board A303 uses the RF signal from the RF Assembly and the mixer injection frequency from the oscillator multiplier board to generate the IF frequency.

CIRCUIT ANALYSIS

RF ASSEMBLY

Pre-Amplifier

The pre-amplifier is present only in UHS receivers, and uses a bi-polar transistor to provide approximately 10 dB gain.

RF from the antenna is link-coupled through helical resonator L2301 to the base of Class A pre-amplifier Q2301. L2301 matches the 50 ohm input to the base of Q2301. The amplified output is coupled through L2302, and connected through W2301 to J1 on Antenna Input

Board A301. P2301 connects to J502 on the IF-Filter Board for regulated +10 Volt supply voltage.

Antenna Input A301A/A301B/A3O1C

An RF signal from the antenna or UHS pre-amplifier is applied to A301 which provides an AC ground between vehicle ground and receiver A-. Resistor R1 prevents a static charge from building up on the vehicle antenna. The output of A301 is coupled through five high Q helical resonators that provide the front end RF selectivity. The helicals are tuned to the in coming frequency by C301 through C305.

Mixer A304

The mixer uses a FET (Q1) as the active device. The FET mixer provides a high input impedance, high power gain and an output relatively free of harmonics (low in intermodulation products).

In the mixer stage, RF from the helical resonators is coupled through L1 and C2 which matches the RF output to the gate of mixer Q5O1. Injection voltage from the multiplier-selectivity stages is applied to the source of the mixer. The 11.2 MHz mixer IF output signal is coupled from the drain of Q1 through Cable W1 to J5O1 on the IF Filter board.

> Ericsson Inc. Private Radio Systems Mountain View Road Lynchburg, Virginia 24502 1-800-528-7711 (Outside USA, 804-592-7711)



Printed in U.S.A.

IF FILTER

Crystal Filter

The output of A303-Q1 is coupled through a tuned circuit (L507 & C515) which matches the out put to the input of the four-pole monolithic crystal filter. The highly-selective crystal filter (FL501 & FL502) provides the first portion of the receiver IF selectivity. The output of the filter is coupled through impedance matching network L503 and C511 to the IF amplifier.

<u>Service Note:</u> Variable capacitor C504 does not require adjustment when performing normal alignment. If the four-pole monolithic crystal filter is replaced, then adjustment of C504 is necessary for optimum IF response.

IF Amplifier

IF Amplifier Q501 is a dual-gate FET. The filter output is applied to Gate 1 of the amplifier, and the output is taken from the drain. The biasing on Gate 2 and the drain load determines the gain of the stage. The amplifier provides approximately 20 dB of IF gain. The output of Q501 is coupled through a network (L504 & C509) that matches the amplifier output to the crystal filter on the IFAS board. The output of the IF-Filter board is applied to the IFAS board through feed-through capacitor C325.

Supply voltage for the RF amplifier and IF-Filter board is supplied from the IFAS board through feed-through capacitor C326.

MODIFICATIONS

Some of the RF amplifier assemblies are not compatible with some of the IF-Filter boards without a modification to the RF assembly mixer board. Refer to the compatibility chart shown below.

RF ASSEMBLY	COMPATIBLE WITH IF-FILTER BOARD
19D417075G9-G18	19C320523G2
19B233690G1-G10	19C331148G1

The following modifications are provided to permit field replacement using incompatible boards or assemblies. Refer to the applicable Outline Diagram for component location and printed wiring board layout.

- To modify RF assemblies 19D417075G9-G18 for operation with IF-Filter board 19C331148G1: add frequency select network Z1 from the drain of mixer FET Q1 to ground. Refer to the Parts List in this manual for the correct part number.
- To modify RF assemblies 19B233690G1-G10 for operation with IF-Filter board 19C320523G2: clip out and remove frequency select network Z1 on the mixer board.

LBI-30032





OUTLINE DIAGRAM 406-512 MHz, RF ASSEMBLY BOARD **19D417075G9-G18, IF FILTER BOARD** 19C320523G2 AND MIXER 19B227059G2

(19D423794, Rev. 10)

LEAD IDENTIFICATION FOR Q2301



VIEW FROM CASE END

NOTE: LEAD ARRANGEMENT, AND NOT CASE SHAPE, IS DETERMINING FACTOR FOR LEAD IDENTIFICATION. TAB INDICATES EMITTER LEAD.

A301A ANT INPUT (FLOATING GROUND)



A301B ANT INPUT (NON-FLOATING GROUND)



LEAD IDENTIFICATION FOR Q1



TRIANGULAR VIEW FROM CASE END

NOTE: LEAD ARRANGEMENT, AND NOT CASE SHAPE, IS DETERMINING FACTOR FOR LEAD IDENTIFICATION. TAB INDICATES EMITTER LEAD.

> A301C ANT INPUT (FLOATING GROUND)



SCHEMATIC DIAGRAM



LBI-30032

SCHEMATIC DIAGRAM 406-512 MHz, RF ASSEMBLY 19D417075G9-G18 AND UHS PRE-AMPLIFIER 19C320527G1-5

(19D423520, Rev. 8), (19B226008, Rev. 7)

IF FILTER BD



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IF FILTER BD	
19C320523G2	Α

SCHEMATIC DIAGRAM **IF FILTER BOARD** 19C320523G2

(19D423519, Rev. 2)

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T	SHOULD	BE M/	ADE	ONLY	WITH
NT	HAVING	THE	SPE	CIFICA	TIONS
TH	E PARTS	LIST I	FOR	THAT	PART

CAPACITOR VALUES IN PICOFARADS (EQUAL TO MICROMICROFARADS) UNLESS FOLLOWED BY UF = MICROFARADS. INDUCTANCE VALUES IN MICROHENRYS UNLESS FOLLOWED BY MH = MILLIHENRYS OR H = HENRYS.



LBI-30032

OUTLINE DIAGRAMS 406-512 MHz, RF ASSEMBLY 19D417075G19-G28, IF-FILTER BOARD 19C331148G1-G2 AND MIXER BOARD 19B227059G3

(19D433377, Rev. 0)



SCHEMATIC DIAGRAMS 406-512 MHz, RF ASSEMBLY 19D417075G19-G28 WITH MIXER BOARD 19B227059G3 AND UHS PRE-AMPLIFIER 19C320527G1-G5

(19D432485, Rev. 2), (19B226008, Rev. 8)



IF FILTER BD

LBI-30032

SCHEMATIC DIAGRAM IF-FILTER BOARD 19C331148G1

(19D432484, Rev. 2)



ALL RESISTORS ARE 1 / 4 WATT UNLESS OTHERWISE SPECIFIED AND RESISTOR VALUES IN OHMS UNLESS FOLLOWED BY K = 1000 OHMS OR MEG = 1,000,000 OHMS. CAPACITOR VALUES IN PICOFARADS (EQUAL TO MICRO-MICROFARADS) UNLESS FOLLOWED BY UN - MICROFARADS. INDUCTANCE VALUES IN MICROHENRYS UNLESS FOLLOWED BY MH = MILLIHENRYS OR H = HENRYS.



SCHEMATIC DIAGRAMS 406-512 MHz, RF ASSEMBLY 19D417075G29-G38 WITH MIXER BOARD 19B227059G4 AND UHS PRE-AMPLIFIER 19C320527G1-G5

(19D433368, Rev. 0), (19B226008, Rev. 8)

IF FILTER BD



LBI-30032

SCHEMATIC DIAGRAM **IF-FILTER BOARD** 19C331148G2

(19D433378, Rev. 2)

		PARTS LIST	SYMBOL	PART NO.	DESCRIPTION	SYMBOL	PART NO.	DESCRIPTION	SYMBOL	PART NO.	DESCRIPTION
	406-	-512 MH2 RECEIVER RF ASSEMBLY IP-FILTER BOARD ASSEMBLY AND UHS PRE-AMPLIFIER	Lì		Part of Printed Wiring Board 19D423518P1.	¥1	54916897114	RF: approx. 5-1/3 inches long. (Iucludes P1).			IF FILTER BOARD 19032052362, 63
SYMBOL	PART NO.	DESCRIPTION	P1		Part of W1.	Z 1	19A134666P1	Proquency network: selective, 470-630 MHz res freq, 500 VDCW; sim to Dilectrou TCS01:NPO:240J:SLAC.	C502 C503	194700005P9 5496267P10	Polyester: 0.022 uP ± 10 %, 50 VDCW. Tantalum: 22 uF ± 20 %, 15 VDCW; sim to Sprague Type 150D.
			Q1	19A134093P1	N Type, field effect; sim to Type 2N4391.	(30)		CAPACITORS	C504	19A700012P1	Variable, ceramic: 2 to 10 pF, 200 VDCW, temp coef -350+500 PPM; sim to Panasonic ECV-12W10X32.
		RF ASSEMBLY 19D417075G9 406-420 MHz FLOATING GRD 19D417075G10 450-470 MHz FLOATING GRD 19D417075G11 470-494 MHz FLOATING GRD	R1	3R151P102K	Composition: 1% chms ±10%, 1/8 w.	thru C305	19C328755P3 19A143476G2	Screw. Wut: thd. mize No. 6-32.	CS08 CS08	194700005P9	Polyester: 0.022 uF ±20%, 50 VDCW.
		190417075G13 405-420 MHz NON FLOATING GRD 190417075G14 450-470 MHz NON FLOATING GRD 190417075G15 470-494 MHz NON FLOATING GRD 190417075G16 494-512 WHz NON FLOATING GRD	¥1	5491689P114	RP: approx. 5-1/8 inches long.	C306 thru C308	19C328755P2	Includes: Screw.	C510	19A116655P19	Electro Motive Type DM-15. Ceramic diac: 1000 pP ±20%, 1000 VDCW; sim to RMC Type JP Discap.
		19D417075G17 420-450 WHz NON FLOATING GRD 19D417075G18 420-450 WHz FLOATING GRD - REV. A 19D417075G19 408-420 WHz FLOATING GRD - REV. A 19D417075G20 450-470 WHz FLOATING GRD - REV. A	A304*		MIXER BOARD 19822705962 (Added by REY, B)	C311+	19A143476G2 5496218P241	Nut: thd. size No. 6-32. Ceramic disc: 10 pF +55, 500 VDCW, temp coef	C511 C512	19A116656P20K0	(Part of L503). Ceramic disc: 20 pF ±10%, 500 VDCW, temp coef
A301A*		190417075621 470-494 MHz FLOATING GRD - REV. A ANTENNA INPUT BOARD 43014 19821994201 450-512 MHz (Deleted in Ge				C325	19B209488P1	Ceramic: 8.8 pF +20%, 500 VDCW; sim to Allen Bradley Style PASD.	C513	194700005P7	0 PPM. Polyester: 0.01 uP ±10%, 50 VDćW.
A301C*		A301C 198219942G2 406-420 MHz (Added to G9 by REV D).	C2 C4*	19470001291 194700219914	Variable. ceramic: 2 to 10 pF, 200 VDCW, temp coef -350+500 PPW; sim to Panasonic ECV-1ZW10X32. Ceramic: 3.3 pF +5%, 100 VDCW, temp coef 0 PPM.	C326	198209488P2	Cornmic: 1000 pF -10+100%, 500 VDCW; sim Allen Bradley Style FA5D.	C5154	5490008P27	Ceramic disc: 1000 pF ±10%, 1000 VDCW; sim to RMC Type JF Discap. Silver mica: 100 pF +5%, 500 VDCW, sim to
C1	7484398P3	Silver mica: 250 pF ±10%, 500 VD(V; sim to	C5	19A116192P1	Ceramic: 0.01 uF ±20%, 50 YDCW; sim to Erie 8121 Special.	L301 L302	19B204938G37 19B219944P1	Coll.	C515B	5490008P24	Silver mica: 75 pP ±5%, 500 VDCW, sim to Electro Motive Type DM-15.
C2 C3	194116679P220K	Silver Mica: 220 pF ±10%, 250 VD(W. Ceramic disc: 27 pF ±5%, 500 VD(W.	C6	194700219P39	Ceramic: 20 pF ±5%, 100 VDCW, temp coef 0 PPM.	tbru L304 L305	198204938G33	Coil.	C516*	19A118656P3K0	Cerumic disc: 3 pF ± 10 %, 500 VDCW, temp coef 0 PPM. Added by REV A.
		0 PPM.	Lì		Part of Printed Board 19D42919491.	L306 and L307	19B219944P5	Coil.	CR501	194116052P1	Silicon, hot carrier: Fwd drop .350 wolts max.
J 1	7104941916	Jack, phono: coaxial; sim to National Tel Barrel Ceramic.	P 1		Part of W1.	L308 L311	198204938641 198204938638	Coil. Coil.	FL501	198219573G3	
Rl	194700106979	RESISTORS Composition: 4.7% ohms <u>+</u> 5%, 1/4 w.	Q1	19A134093P1	N Type, field effect; sim to Type 2N4391.	L312 tbru L314 L315	19821994492		F 1.502		(Part of FL501).
A3018*		ANTENNA INPUT PLATE 194137683G2 (Added to G13-G16 by REV. A)	Rl	3R151P102J	Composition: 1K ohms ±5%, 1/8 w.	L316 and L317	198219944P6	Co11.	J 501	19 <u>4</u> 700049P2	Connector, receptacle: 500 VDCW maximum; sim to NTTF-1058.
31	7104941920	JACKS AND RECEPTACLES	¥1	5491689P114	RF: approx. 5-1/8 inches long. (Includes P1).	L318 L321	198204938642 198204938639	Coil. Coil.	J502 J503 and	4033513P1 194116975P1	Contact, electrical: sim to Bead Chain 193-4. Receptacle, wire spring.
A301B*		ANTENNA INPUT PLATS 19A137683G1 (Deleted 1m G13-G16 by REV A)	A305		KIXER BOARD 19822705963	L322 thru L324	19821994493	Coil.	1502*	7488079948	Coll BE: 27 W 105 1 4 cher DC and mark at
	2104041020	JACKS AND RECEPTACLES	C2	19A700012P1	Variable, ceramic: 2 to 10 pF, 200 VDCF, temp ccef -350+500 PPM; sim to Panasonic ECV-1ZW10X32.	L326 and L327	19321994477	Coil.	1.503	19032014164	to Jeffers 4422-9. Deleted by REV A. Coil. Includes:
	104541720	RESISTORS	C5	19A116192P1	Ceramic: 0.01 uF ±20%, 50 VDCW; sim to Brie 8121 Special.	L328 L331	198204938G43 198204938G40	Coil. Coil.	L504	5493185P9 19C320141G29	Tubing slug. Coil. Includes:
R1 A303+	19A700106P79	Composition: 4.7K chms ±5%, 1/4 *.	C7	194700219P14	Ceramic: 20 pF <u>+</u> 5%, 100 VDCW, temp coef 0 PPM. Ceramic: 3.3 pF <u>+</u> 5%, 100 VDCW, temp coef 0 PPM.	L332 thru L334	198219944P4	Coil.	1,505 1,506	194700024925	Coil, RF: 10.0 uH ±10%, 3.70 ohms DC res max. (Part of Printed Board 190320522P1).
		(Deleted by REV. B)	Li	10170010001	Part of Printed Board 19D429194P1.	L335 L336 2nd	198204938G36 198219944P8	Coil. Coil.	L507 L508	19C321810G1 19A700000P114	Coil. Coil, RP: 1.5 uH ±10%; sim to Jeffers 4412-7K.
C1 C2	19A116080P103 19A700012P1	Polyester: 0.022 µP ±10%, 50 VDCW. Variable, ceramic: 2 to 10 pF, 200 VDCW, temp	52	198/0012291	PLEGS	L337 L338 L351	19B204938G44 19B204938G47	Coil. Coil.	P501		Part of \$601
C3	19A116656P2QKO	Coer -350+500 PPM; sim to Panagonic ECV-12#10X32. Ceramic disc: 20 pF <u>+</u> 10%. 500 VDCM, temp coef 0 PPM.	P1		Part of W1.	L352 thru L354	19821994499	Coil.	7301		
C4*	194700219914	Ceramic: 3.3 pP ±5%, 100 VDCW, texp coef 0 PPM. Earlier than REV A:	QI	19A134093P1	N Type, field effect; sim to Type 2N4391.	L355 L356 and	198204938G48 198219944P10	Coil. Coil.	Q501	19A116818P4	N Channel, field effect.
	1941106569580	Ceramic disc: 3 pr <u>-</u> 10%, 500 VDCW, temp coer 0 PPM.	Rl	3R151P102J	Composition: 1K ohms ±5%, 1/8 w.	L357 L358	198204938Ç49	Coil.	R501 R502	194700106P87 194700106P77	Composition: 10K ohms ±5%, 1/4 w. Composition: 3.9K ohms ±5%, 1/4 w.
*COMPON	IENTS ADDED, DI	ELETED OR CHANGED BY PRODUCTION CHANGES						1			

PARTS LIST

SYMBOL	PART NO.	DESCRIPTION	SYMBOL	PART NO.	DESCRIPTION]				SYMBOL	PART NO.	DESCRIPTION
R503 R504 R506	194700106P47 194700106P31 194700106P71	Composition: 220 ohms 15%, 1/4 w. Composition: 47 ohms 15%, 1/4 w. Composition: 2.2K ohms 15%, 1/4 w.	Q2301	1 94116859 92	Silicon, NPN.				R7 ASSEMBLY 19823369001-620 18805 5	P1		
W 501	19A129947G7	Cable: orange, No. 22 stranded, approx. 7-1/2 inches. (Includes P501).	R2301 R2302*	194700106P91 194700136P87	Composition: 15% ohms ±5%, 1/4 v. Composition: 10% ohms ±5%, 1/4 v.	[SYMBOL	PART NO.	DESCRIPTION	Q1 Q1	19A134093P1 19A700060P2	N Type, field effect; sim to Type 2N4391. (Used in G3). N Type, field effect. (Used in G4).
		UHS RP PRE-AMPLIFIER 19C320527G1 406-420 MHz (LL) 19C320527G2 450-470 MHz (L) 19C320527G3 470-494 MHz (M) 19C320527G4 494-512 MHz (H) 19C320527G5 420-450 MHz (LM)	R2303 R2304	194700136P83 194700136P57 194700106P39	In RSV A & earlier: Composition: 6.8K ohms ±55, 1/4 w. Composition: 560 ohms ±55, 1/4 w. Composition: 100 ohms ±55, 1/4 w.				STANDARD 198233690G1, 11 406-420 MHz 198233690G2, 12 420-450 MHz 198233690G2, 12 430-470 MHz	RI	3R151P102J	
C2301	19A116656P3J8		R2305*	194700106P63	Composition: 1K ohms ±5%, 1/4 w. In REV A: Composition: 320 ohms ±5%, 1/4 w. Added by REV A.				19233690C4, 14 470-494 MHz 198233690C5, 15 494-512 MHz NON PLOATING GROUND ONLY 198233690C6, 16 406-420 MHz 192233690C7, 17 420-450 MHz	Wl	4391689P114	Cable, RF: approx 5-1/2 inches long. (Includes P1).
C2302* C2302A*	19A116679P220K 19A134666P2	Silver Mica: 220 pF ±10%, 250 VDCW. Deleted by REV A. Frequency network: selective, 460-600 MHz res freq, 500 VDCW; sim to Dilectron TC501:NPO:270J:SLAC. Added by G1 & G5 by REV A.	V23 01	5491689794	RP: approx. 3 inches long, (Includes P2302).				19823369006, 18 450-470 MHz 19823369009, 19 470-494 MHz 198233890090, 20 494-512 MHz RP CIRCUIT	21	19413466691	Prequency network: selective, 470-630 MHz res. freq, 500 VDCW; sim to Dilectron TC501:NPO:240J:SLAC.
C2302B*	19A134666P1 19A116656P18J8	Prequency network: selective, 470-630 MHz res freq, 500 VDCF; sim to Dilectrom TC501:NPO:240J/SLAC. Added to G2-G4 by REV A. Ceramic disc: 18 pP ±5%, 500 VDCF, temp coef -80 PPM.		19850112161 19822710161 1982092097304	Casting, RF Circuit. Cover, RF Circuit. Tap screw. Phillips POZIDEIVS: No. 6-32 - 3/8				100-17075620, 30 420-420 HEZ FLOATING GED 100417075620, 30 420-450 HEZ FLOATING GED 100417075622, 31 450-470 HEZ FLOATING GED 100417075622, 32 470-494 HEZ FLOATING GED 100417075623, 33 494-512 HEZ FLOATING GED 100417075623, 34 408-420 HEZ NON FLOATING GED 100417075625, 3420-450 HEZ NON FLOATING GED	C301 thru C305	19032875593 19414347662	Includes: Screw. Nut: thd. size No. 6-32.
C2305 C2306+	19A116656P20K0 5490008P127	Ceramic disc: 20 pP ±10%, 500 VDCF, temp coef 0 PPM. Silver mica: 100 pP ±10%, 500 VDCF, sim to Electro Motive Type DM-15.		19C328755P3 19C328755P2	(Secures RF Circuit Cover). Screw. (Part of C301-C305). Screw. (Part of C306-C306).		43014		19D417075G26, 38 450-470 HHZ NON FLOATING GRD 19D417075G27, 37 470-494 HHZ NON FLOATING GRD 19D417075G28, 38 494-512 HHZ NON FLOATING GRD COMPONENT BOARD	C306 tbru C308	19C328755P2 19A143476G2 5496218P241	Includes: Screw. Nut: thd. mize No. 6-32. Ceramic disc: 10 pF +5% 500 VDCW. teen coef
C2307*	19A116679P100K 19A116656P24J0	Earlier than REV A: Silver Mica: 100 pF ±10%, 250 VDCW, Ceramic disc: 24 pP ±5%, 500 VDCW, temp coef 0 PPM.		19A14347602 4031594P1 19B219470P2 19A12942461	Nut: thd. size No. 6-32. (Part of C301-C308). Insulator. (Used with C504 on IP Filter Board). Shield. (Used with IF Filter Board). Can. (Used with 1401-1403 1501 1503 1504).		ABOIC	748439873	A301A 19921994201 A301C 199219942C1 	C325 C326	198209488P1	-80 PPM. Ceramic: 6.8 pF +20%, 500 VDCW; eim to Allen Bradley Style FASD. Ceramic: 1000 pF -10+100%, 500 VDCW; sim Allen
C2308*	19A116679P220K 5490008P135	Earlier than REV A: Silver Mica: 220 pF ±10%, 250 VDCW. Silver mica: 220 pF ±10%, 500 VDCW, sim to		19A127(60P2 4035306P59 403530(P23	Can. (Used with L2301). Washer, fiber. (Used with PL501, PL502). Washer, fiber. (Used with J501, J2301).		C2 C3	194700015P37 194116656P27J0	Underwood Type 71HF. Teflon/Mica: 220 pF ±5%, 250 VDCW. Ceramic disc: 27 pP ±5%, 500 VDCW, temp coef 0 PPM.	L301	19B204938G37	Coil.
C2309	19A116679P100K 19A116656P30J8	Electro Motive Type DM-15. Earlier than REV A: Silver Mica: 100 p7 ±10%, 250 VDCW. Ceramic disc: 30 p7 ±55, 500 VDCW, temp cosf		19A701232P1 4035306P11 4035306P23	Insulator disk. (Used with Q2301). Washer, fiber: 1/8 dia. (Used with Q501). Washer, fiber. (Used with J501).		J 1	7104841916	JACKS AND RECEPTACLES	L302 thru L304 L305	198219944P1 198204938G33	Coll.
C2310*	19A116656P20K0 19A134666P2	-B0 PPM. Ceramic disc: 20 pF ±10%, 500 VDCW, temp coef 0 PPM. Deleted by R2V A. Frequency network: selective, 480-700 KHz res					B1	194700108F79	Composition: 4.7% ohms ±5%, 1/4 w.	L308 and L307 L308 L311	198219944P5 198204938G41 198204938G38	Coil. Coil. Coil.
C2310B*	19A134666P1	Ireq, SUU VDCF; sim to Dilectron TC501:NP0:270J:SLAC. Added by REV B. Prequency network: selective, 470-630 MHz res freq, 500 VDCW; sim to Dilectron TC501:NP0:240J:SLAC. Added by REV B.					_3018 J1	7104941920	ISAI3768362 JACKS AND RECEPTACLESJack, phono: convial.	L312 thru L314 L315	19821984492 198204838634	Co11. Co11.
J2301	19470004992	Connector, receptacle: 500 VDCV maximum; sim to NTTF-1058.					A 305		MIXER BOARD 19322705963, 64	L316 and L317 L318	198219944P6 198204938642	Coil.
1.2301LL 1.2301L	19D413078G3 19D413078G5						C2 C5	194700012P1 194116192P1	Variable, ceramic: 2 to 10 pF, 200 VDCW, temp coef -350+500 PPM; sim to Panamonic ECV-12W10X32. Ceramic: 0.01 uF <u>+</u> 20%, 50 VDCW; sim to Erie 8121	L321 L322 tbru L324	198204938639 198219944P3 198204938635	Coil. Coil.
L2301M L2301H L2301LM L2302*	19D413078G6 19D413078G7 19D413078G9 19B209420P101	Helical resonator. Helical resonator. Helical resonator. Coil, RF: .10 uH t105 0.8 obms DC res must ris					C8 C7	194700219P39 194700219P14	Special. Ceramic: 20 pF $\pm 5\%$, 100 VDCW, temp coef 0 PPM. Ceramic: 3.3 pF $\pm 5\%$, 100 VDCW, temp coef 0 PPM.	L326 and L327 L328	198219944P7	Coll.
	19A129716G4	to Jeffers 4416-12. Earlier than REV A: Coil.					L1 L2	194700122P1	(Part of Printed Board 190429194P1). Torridal core.	L331 L332 thru L334	198204938640 198219944P4	Coil. Coil.
P2301 P2302	19A702402P2	Contact, electrical; sim to AMP 42827-2. (Part of W2301).										

*COMPONENTS ADDED, DELETED OR CHANGED BY PRODUCTION CHANGES

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LBI-30032
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SYMBOL	PART NO.	DESCRIPTION	SYMBOL	PART
L335	198204938G36	Coil.		
L336	19821994498	Coil.	Q501	19A11681
and L337				
L338	198204938644	Coll.		
L351	198204938647	Coil.	£501	19A70010
L352	198219944P9	Coil.	R502	19A70010
1354			R503	19470010
1,355	198204938P48	Coil.	R504	19A70010
L356 and L357	198219944F10	Coil.	R506	19470010
L356	198204938P49	Coil.	₩501	19412994
		IF FILTER BOARD 19C331148C1 19C331148G2		
				19850112
C502	T644ACP322K	Polyester: 0.022 uF ±10%, 50 VDCF.		19822710
C503	19A701534P8	Tantalum: 22 uP ±20%, 16 VDCW.		19820920
C504	194700012P1	Variable, ceramic: 2 to 10 pF, 200 VDCW, temp coef -350+500 PPW; sim to Panasonic ECV-12W10X32		19C32875
C505 thru	19A143477P17	Polyester: 0.22 uF ±20%, 50 VDCW.		19032875
C506				40214040
C509	5490008P139	Silver mica: 330 pP ±10%, 500 VDCW, sim to Electro Motive Type DM-15.		4031584P
C510	194700233P7	Ceramic: 1000 pF ±20%, 50 VDCW.		19419049
C511		(Part of L503).		40353045
C512	19A116656P20X0	Ceramic disc: 20 pF ±10%, 500 VDCW, temp coef 0 PPM.		403530AP
C513	1644ACP310K	Polyester: .010 uF ±10%, 50 VDCW.		40353062
C514	194700233P7	Ceramic: 1000 pF ±20%, 50 VDCW.		19412971
C515	5490008F24	Silver mica: 75 pF +5%, 500 VDCW, sim to Electro Notive Type DW-15,		
C516	1 947 02236F25	Cermaic: 10 pP ±0.5 pP, 50 VDCW, temp coef 0 ± 30 PPM/*C.		
		DIODES AND RECTIPIERS		
CR501	19A700047P1	Silicon, 100 mW continous dissipation.		
		FILTERS		
PL501	19B219573G3	Crystal: Resonator A = 11,200.000; Resonator B = 11,196.024 kHz.		
FL502		(Part of FL501).		
J501	19A700049P2	Connector, receptacle: 500 VDCW maximum; sim to		
1502	403351321	NTTF-1058.		
J503	19A116975P1	Contract, electrical: sim to Bead Chain 193-4.		
and J504		COSTRUT, GIECTFICEI.		
		INDUCTORS		
L503	19C320141G4	Coil. Includes:		
	5493185P9	Tuning slug.		
L504	19C320141G29	Coil. Includes;		
	5493185P9	Tuning slug.		
1506	194700024P25	Coil, RF: 10.0 uH ±10%, 3.70 ohms DC res max.		
L507	19032181001	(Part of Printed Board 19C331147P1).		
L508	19A7000009114	Coil, RF: 1.5 uH +10%: wim to Jofford 4410-78		
		work, mt. 1.5 um g108; Sim to Jerrers 9912-7K.		
P501		(Part of TEQ.)		
5-001		(Part of #501).		

OL	PART NO.	DESCRIPTION
		TRANSISTORS
	19A116818P4	N Channel, field effect.
	194700106287	Composition: 10T obstation: 1/4 =
	19A700106P77	Composition: 3.9K ohms +5%, 1/4 w.
	19A700106P47	Composition: 220 ohms ±5%, 1/4 w.
	19A700106P31	Composition: 47 ohms ±5%, 1/4 w.
	19A700106P71	Composition: 2.2K ohms ±5%, 1/4 w.
	19812994767	Cable: orange, No. 22 stranded, approx. 7-1/2 inches. (lacludes P501).
	198501121G1	Casting, RF Circuit.
	19B227101G1	Cover, RF Circuit.
	198209209P306	Tap screw, Phillips POZIDRIV®: No. 6-32 x 3/8. (Secures RF Circuit Cover).
	19C328755P3	Screw. (Part of C301-C305).
	19C328755P2	Screw. (Part of C306-C308).
	19A143476G2	Nut: thd. size No. 6-32, (Part of C301-C308).
	4031594P1	Insulator. (Used with C504 on IF Filter Board).
	19412942441	Can. (Baed with 1503 1504 1503).
	4035306P59	Vasher, fiber. (Used with PL501. PL502).
	4035306723	Tamber, fiber. (Dsed with J501).
	4035306P11	Washer, fiber: 1/8 dia. (Used with Q501).
	19A129715G1	Adapter Board.

PRODUCTION CHANGES

Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter", which is stamped after all the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for descriptions of parts affected by these revisions.

REV. A - <u>RF Assembly 19D417075G0-12</u>

To improve receiver sensitivity. Changed C4.

REV. B - <u>RF Assembly 19D417075G0-12</u>

To incorporate new mixer board. Replaced A303 (19B227059G1) with A304 (19B227059G2).

Schematic Diagram Was:

RF ASSEMBLY 19D417075



PRODUCTION CHANGES - (Continuation)

Outline Diagram Was:



REV. A - <u>IF - Filter Board 19C320523G2</u> To improve operation. Replaced L502 with L508, added C516.

REV. A - RF Assembly 19D417075G13-G16

REV. C - <u>RF Assembly 19D417075G9-G12</u> To improve sensitivity. Deleted A304-C4.

REV. D - <u>RF Assembly 19D417075G9</u> To improve receiver sensitivity in 406 to 420 MHz range. Added A301C.

REV. A - <u>UHS Pre-Amplifier</u> To incorporate new coil (L2302). Changed L2302, C2302, C2306, C2307 and C2308. Deleted C2310 and added R2305.

REV. B - <u>UHS Pre-Amplifier</u> To improve receiver sensitivity. Changed R2302 and R2305. Added C2310.

REV. A - <u>RF Assembly 19D417075G19-G28</u> <u>IF Filter Board 19C331148G1</u> To improve operation of UHF mixer circuit. Added C7 and L2.

REV. B - UHS Pre-Amplifier To improve receiver sensitivity. Changed R2302 and R2305. Added C2310.

- REV. A IF Filter Board 19C331148G2 Q501 no longer available. Was 19A116818P1. Added C516.
- REV.B IF Filter Board 19C331148G2 Relocate C516 to Q501-D to ground.

LBI-30032